INTEGRATED CIRCUITS



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TDA4780

RGB video processor with automatic cut-off control and gamma adjust

FEATURES

- Gamma adjust
- Dynamic black control (adaptive black)
- All input signals clamped on black-levels
- Automatic cut-off control, alternative: output clamping on fixed levels
- Three adjustable reference voltage levels via l²C-bus for automatic cut-off control
- Luminance/colour difference interface
- Two luminance input levels allowed
- Two RGB interfaces controlled by either fast switches or by I²C-bus
- Two peak drive limiters, selection via I²C-bus
- Blue stretch, selection via I²C-bus
- Luminance output for scan velocity modulation (SCAVEM)
- Extra luminance output; same pin can be used as hue control output e.g. for the TDA4650 and TDA4655
- Non standard operations like 50 Hz/32 kHz are also possible
- Either 2 or 3 level sandcastle pulse applicable
- High bandwidth for 32 kHz application
- White point adjusts via I²C-bus
- Average beam current and improved peak drive limiting
- Two switch-on delays to prevent discoloration during start-up
- All functions and features programmable via l²C-bus
- PAL/SECAM or NTSC matrix selection.

GENERAL DESCRIPTION

The TDA4780 is a monolithic integrated circuit with a luminance and a colour difference interface for video processing in TV receivers. Its primary function is to process the luminance and colour difference signals from a colour decoder which is equipped e.g. with the multistandard decoder TDA4655 or TDA9160 plus delay line TDA4661 or TDA4665 and the Picture Signal Improvement (PSI) IC TDA467X or from a feature module.



The required input signals are:

- Luminance and negative colour difference signals
- 2 or 3-level sandcastle pulse for internal timing pulse generation
- I²C-bus data and clock signals.

Two sets of analog RGB colour signals can also be inserted, e.g. one from a peritelevision connector (SCART plug) and the other one from an On-Screen Display (OSD) generator. The TDA4780 has I²C-bus control of all parameters and functions with automatic cut-off control of the picture tube cathode currents. It provides RGB output signals for the video output stages. In clamped output mode it can also be used as an RGB source.

The main differences with the sister type TDA4680 are:

- Additional features, namely gamma adjust, adaptive black, blue stretch and two different peak drive limiters
- The measurement lines are triggered by the trailing edge of the vertical component of the sandcastle pulse
- I²C-bus receiver only. Automatic white level control is not provided; the white levels are determined directly by the I²C-bus data.
- The TDA4780 is pin compatible (except pin 18) with the TDA4680. The I²C-bus slave address can be used for both ICs. When a function of the TDA4780 is not included in the TDA4680, the I²C-bus command is not executed. Special commands (except control bit FSWL) for the TDA4680 will be ignored by the TDA4780.

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QUICK REFERENCE DATA

SYMBOL	PARAMETER	MIN.	TYP.	MAX.	UNIT
VP	supply voltage (pin 5)	7.2	8.0	8.8	V
I _P	supply current (pin 5)	80	100	120	mA
V _{8(p-p)}	luminance input (peak-to-peak value) (C)VBS	_	0.45/1.43	-	V
V _{6(p-p)}	–(B – Y) input (peak-to-peak value)	_	1.33	_	V
V _{7(p-p)}	–(R – Y) input (peak-to-peak value)	_	1.05	_	V
V ₁₄	three-level sandcastle pulse				
	H + V	_	2.5	_	V
	Н	_	4.5	_	V
	ВК	-	8.0	-	V
	two-level sandcastle pulse				
	H + V	_	2.5	_	V
	BK	_	4.5	_	V
Vi	RGB input signals at pins 2, 3, 4, 10, 11 and 12 (black-to-white value)	-	0.7	-	V
V _{o(p-p)}	RGB output at pins 24, 22 and 20 (black-to-white value)	-	2.0	-	V
T _{amb}	operating ambient temperature	-20	-	+70	°C

ORDERING INFORMATION

ТҮРЕ		PACKAGE	
NUMBER	NAME	DESCRIPTION	VERSION
TDA4780	DIP28	plastic dual in-line package; 28 leads (600 mil)	SOT117-1

BLOCK DIAGRAM





Preliminary specification

RGB video processor with automatic cut-off control and gamma adjust

PINNING

SYMBOL	PIN	DESCRIPTION			
FSW ₂	1	fast switch 2 input			
R ₂	2	red input 2			
G ₂	3	green input 2			
B ₂	4	blue input 2			
V _P	5	supply voltage			_
-(B - Y)	6	colour difference input –(B – Y)	FSW ₂	U	28 SCL
-(R - Y)	7	colour difference input –(R – Y)	R ₂ 2		27 SDA
Y	8	luminance input	G ₂ 3		
GND	9	ground			
R ₁	10	red input 1	B ₂ 4		25 C _R
G ₁	11	green input 1	V _P 5		24 R _O
B ₁	12	blue input 1	-(B - Y) 6		23 C _G
FSW ₁	13	fast switch 1 input	-(R - Y) 7		22 G _O
SC	14	sandcastle pulse input	Y 8	TDA4780	21 C _B
BCL	15	average beam current limiting input	GND 9		20 BO
C _{PDL}	16	storage capacitor for peak limiting	R ₁ 10		19 CI
CL	17	storage capacitor for leakage current compensation			
C _{PDST}	18	storage capacitor for peak dark	G ₁ 11		18 C _{PDST}
CI	19	cut-off measurement input	B ₁ 12		17 CL
B _O	20	blue output	FSW ₁ 13		16 C _{PDL}
C _B	21	blue cut-off storage capacitor	SC 14		15 BCL
G _O	22	green output		MGE87	74
C _G	23	green cut-off storage capacitor			
R _O	24	red output			
C _R	25	red cut-off storage capacitor			
YHUE	26	Y-output/hue adjust output			
SDA	27	I ² C-bus serial data input/acknowledge output	Fig 3	Pin configu	uration.
SCL	28	I ² C-bus serial clock input	1.9.0	. In connige	

FUNCTIONAL DESCRIPTION

Signal input stages

The TDA4780 contains 3 sets of input signal stages for:

- 1. Luminance/colour-difference signals:
 - a) Y: 0.45 V (p-p) VBS or 1.43 V (p-p) VBS, selectable via l²C-bus.
 - b) -(R Y): 1.05 V (p-p).
 - c) -(B Y): 1.33 V (p-p).

The capacitively coupled signals are matrixed to RGB signals by either a PAL/SECAM or NTSC matrix (selected via I²C-bus).

- (RGB)₁ signals (0.7 V (p-p) VB), capacitively coupled (e.g. from external source).
- 3. (RGB)₂ signals (0.7 V (p-p) VB), capacitively coupled (e.g. videotext, OSD).

All input signals are clamped in order to have the same black levels at the signal switch input. Displayed signals must be synchronous with the sandcastle pulse.

Signal switches

Both fast signal switches can be operated by switching pins (e.g. SCART facilities) or set via the l^2 C-bus. With the pin FSW₁ the Y-CD signals or the (RGB)₁ signals can be selected, with pin FSW₂ the above selected signals or the (RGB)₂ signals are enabled. During the vertical and horizontal blanking time an artificial black level equal to the clamped black level is inserted in order to clip off the sync pulse of the luminance signal and to suppress hum during the cut-off measurement time and eliminate noise during these intervals.

Saturation, contrast and brightness adjust

Saturation, contrast and brightness adjusts are controlled via the I²C-bus and act on Y, CD as well as on RGB input signals. Gamma acts on the luminance content of the input signals.

Gamma adjust

The gamma adjust stage has a non-linear transmission characteristic according to the formula $y = x^{gamma}$, where x represents the input and y the output signal. If gamma is smaller than unity, the lower parts of the signal are amplified with higher gain.

Adaptive black (ADBL)

The adaptive black stage detects the lowest voltage of the luminance component of the internal RGB signals during the scanning time and shifts it to the nominal black level. In order to keep the nominal white level the contrast is increased simultaneously.

Blue stretch (BLST)

The blue stretch channel gets additional amplification if the blue signal is greater than 80% of the nominal signal amplitude. In the event the white point is shifted towards higher colour temperature so that white parts of a picture seem to be brighter.

Measurement pulse and blanking stage

During the vertical and horizontal blanking time and the measurement period the signals are blanked to an ultra black level, so the leakage current of the picture tube can be measured and automatically compensated for.

During the cut-off measurement lines (one line period for each R, G or B) the output signal levels are at cut-off measurement level.

The vertical blanking period is timed by the sandcastle pulse. The measurement pulses (leakage, R, G and B) are triggered by the negative going edge of the vertical pulse of the sandcastle pulse and start after the following horizontal pulse.

The IC is prepared for 2f_H (32 kHz) application.

Output amplifier and white adjust potentiometer

The RGB signals are amplified to nominal 2 V (p-p), the DC-levels are shifted according to cut-off control. The nominal signal amplitude can be varied by \pm 50% by the white point adjustment via the l²C-bus (individually for RGB respect).

Automatic cut-off control

During leakage measurement time the leakage current is compensated in order to get a reference voltage at the cut-off measurement info pin. This compensation value is stored in an external capacitor. During cut-off current measurement times for the R, G and B channels, the voltage at this pin is compared with the reference voltage, which is individually adjustable via I²C-bus for each colour channel. The control voltages that are derived in this way are stored in the external feedback capacitors. Shift stages add these voltages to the corresponding output signals. The automatic cut-off control may be disabled via the I²C-bus. In this mode the output voltage is clamped to 2.5 V. Clamping periods are the same as the cut-off measurement periods.

Signal limiting

The TDA4780 provides two kinds of signal limiting. First, an average beam limiting, that reduces signal level if a certain average is exceeded. Second, a peak drive limiting, that is activated if one of the RGB signals even shortly exceeds a via I²C-bus adjusted threshold. The latter can be either referred to the cut-off measurement level of the outputs or to ground.

When signal limiting occurs, contrast is reduced, and at minimum contrast brightness is reduced additionally.

Sandcastle decoder and timer

A 3-level detector separates the sandcastle pulse into combined line and field pulses, line pulses, and clamping pulses. The timer contains a line counter and controls the cut-off control measurement.

Application with a 2-level 5 V sandcastle pulse is possible.

Switch on delay circuit

After switch on all signals are blanked and a warm up test pulse is fed to the outputs during the cut-off measurement lines. If the voltage at the cut-off measurement input exceeds an internal level the cut-off control is enabled but the signal remains still blanked. In the event of output clamping, the cut-off control is disabled and the switch on procedure will be skipped.

Y output and hue adjust

The TDA4780 contains a D/A converter for hue adjust. The analog information can be fed, e.g. to the multistandard decoder TDA4650 or TDA4655. This output pin may be switched to a Y output signal, which can be used for scan velocity modulation (SCAVEM). The Y output is the Y input signal or the matrixed (RGB) input signal according to the switch position of the fast switch.

I²C-bus

The TDA4780 contains an I^2C -bus receiver for control function.

ESD protection

The Pins are provided with protection diodes against ground and supply voltage (see Chapter "Internal pin configurations"). I²C-bus input pins do not shunt the I²C-bus signals in the event of missing supply voltage.

EMC

The pins are protected against electromagnetic radiation.

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I²C-BUS RECEIVER

Table 1 Slave address; note 1

A6	A5	A4	A3	A2	A1	A0	W
1	0	0	0	1	0	0	0

Note

- 1. Explanation for the cell contents of the table:
 - a) W means write.

Table 2 Slave receiver format (write mode; BREN = 0); note 1

S	SLAVE ADDRESS	Α	SUBADDRESS ⁽²⁾	Α	DATA BYTE	Α	Ρ
					n data bytes with auto-increment of subaddresses		

Notes

- 1. Explanation for the cell contents of the table:
 - a) S means START condition.
 - b) P means STOP condition.
 - c) A means acknowledge.
- 2. All subaddresses within the range 00H to 0FH are automatically incremented. The subaddress counter wraps around from 0FH to 00H. Only in this event 0FH will be acknowledged.

Subaddresses outside the range 00H to 0EH are not acknowledged by the device and neither auto-increment nor any other internal operation takes place.

All eight bits of the subaddress have to be decoded by the device.

Table 3Slave receiver format (write mode; BREN = 1); note 1

S	SLAVE ADDRESS	Α	SUBADDRESS	Α	DATA BYTE ⁽²⁾	А	Ρ

Notes

- 1. Explanation for the cell contents of the table:
 - a) S means START condition.
 - b) P means STOP condition.
 - c) A means acknowledge.
- 2. Auto-increment is not possible.







Table 4 Signal input selection and effect on adaptive black measurements by fast source switches and I²C-bus; note 1

I ² C-B	US CONT	ROLLED	BITS	ANALOG	SWITCH	SELECTED SIGNALS					
FSON2	FSDIS2	FSON1	FSDIS1	FSW2 (pin 1)	FSW1 (pin 13)	RGB ₂ (pins 2, 3 and 4)	ADBL	RGB ₁ (pins 10, 11 and 12)	TV (pins 6, 7 and 8)		
L	L	L	L	L	L		active		ON		
				L	Н		active	ON			
				Н	Х	ON	inactive				
L	L	L	Н	L	Х		active		ON		
				Н	Х	ON	inactive				
L	L	Н	Х	L	Х		active	ON			
				Н	Х	ON	inactive				
L	Н	L	L	Х	L		active		ON		
				Х	Н		active	ON			
L	Н	L	Н	Х	Х		active		ON		
L	Н	Н	Х	Х	Х		active	ON			
Н	L	Х	Х	L	Х	ON	active				
				Н	1	ON	inactive				
Н	Н	Х	Х	Х	Х	ON	active				

Note

1. Explanation for the cell contents of the table:

a) H = set to logic 1 or analog switch (pins 1 and 13) to >0.9 V.

b) L = set to logic 0 or analog switch (pins 1 and 13) to <0.4 V.

c) X = don't care.

d) ON = this signal is selected.

Table 5 Crosstalk; note 1

FSW1	FSW2	CROSSTALK	AT 4 MHz MAXIMUM VALUE (dB)	AT 8 MHz MAXIMUM VALUE (dB)	AT 13 MHz MAXIMUM VALUE (dB)
L	L	$RGB_1 \rightarrow Y, CD$	-58	-55	-50
		$RGB_2 \rightarrow Y, CD$	-58	-55	-50
L	Н	$Y, CD \rightarrow RGB_1$	-51	-50	-47
		$RGB_2 \to RGB_1$	-58	-55	-50
L	Н	$Y, CD \rightarrow RGB_2$	-51	-50	-47
		$RGB_1 \to RGB_2$	-58	-55	-50
Н	Н	$Y, CD \rightarrow RGB_2$	-51	-50	-47
		$RGB_1 \to RGB_2$	-58	-55	-50

Note

- 1. Explanation for the cell contents of the table:
 - a) H = set to logic 1.
 - b) L = set to logic 0.

FUNCTION		DATA BYTE								
FUNCTION	SUBADDRESS	D7	D6	D5	D4	D3	D2	D1	D0 ⁽³⁾	
Brightness	00H	L	L	A05	A04	A03	A02	A01	A00	
Saturation	01H	L	L	A15	A14	A13	A12	A11	A10	
Contrast	02H	L	L	A25	A24	A23	A22	A21	A20	
Hue	03H	L	L	A35	A34	A33	A32	A31	A30	
Red gain	04H	L	L	A45	A44	A43	A42	A41	A40	
Green gain	05H	L	L	A55	A54	A53	A52	A51	A50	
Blue gain	06H	L	L	A65	A64	A63	A62	A61	A60	
Red level reference	07H	L	L	A75	A74	A73	A72	A71	A70	
Green level reference	08H	L	L	A85	A84	A83	A82	A81	A80	
Blue level reference	09H	L	L	A95	A94	A93	A92	A91	A90	
Peak drive limit	0AH	L	L	AA5	AA4	AA3	AA2	AA1	AA0	
Gamma	0BH	L	L	AB5	AB4	AB3	AB2	AB1	AB0	
Control register 1	0CH	SC5	DELOF	BREN	Х	NMEN	Х	Х	Х	
Control register 2	0DH	Х	HDTV	FSBL	BCOF	FSDIS2	FSON2	FSDIS1	FSON1	
Control register 3	0EH	ADBL	YHI	MOD2	BLST	YEXH	RELC	TCPL	L	

Notes

- 1. Explanation for the cell contents of the table:
 - a) L = set to logic 0.
 - b) X means don't care but for software compatibility with further video ICs with the same slave address, it is recommended to set all these bits to logic 0.
- 2. After power on reset all alignment registers are set to 01H.
- 3. The least significant bit of the analog alignment register.

Table 7	RGB processor mode bits control register
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SYMBOL	PARAMETER	CONDITIONS
Control re	egister 1	
SC5	sandcastle 5 V	0 = 3-level sandcastle pulse
		1 = 2-level sandcastle pulse
DELOF	delay of leading edge of	0 = delay
	clamping pulse switched off	1 = no delay
BREN	buffer register enable	0 = new data are executed just after reception
		1 = data is held in a latch (buffer register) and will be transferred to their destination register within the next vertical blanking interval; the device does not acknowledge any new data transfer until the internal transfer to the destination register has been completed
NMEN	NTSC matrix enable; note 1	0 = PAL matrix
		1 = NTSC matrix; hue position set on -2 degrees
Control re	egister 2	
HDTV	HDTV / progressive scan for	0 = 272 (PAL), 224 (NTSC) lines
	ADBL line counter	1 = 544 (PAL), 448 (NTSC) lines
FSBL	full screen black level, e.g. for	0 = normal mode
	optical measurement	1 = cut-off measurement level during full field, brightness inactive
BCOF	internal black level control off	0 = automatic cut-off control active
		1 = RGB outputs clamped to fixed DC levels
FSON2	fast switch 2 on	see Table 4
FSDIS1	fast switch 1 disable	
FSDIS2	fast switch 2 disable	
FSON1	fast switch 1 on	
Control re	egister 3	
ADBL	adaptive black	0 = off
		1 = on
YHI	Y high level	0 = input = 0.315 V (p-p) (black-white)
		1 = input = 1.0 V (p-p) (black-white)
MOD2	modus 2	0 = inactive; (BCOF = 0) AND (MOD2 = 1) is senseless, no output stabilization
		1 = output clamp without brightness adjust, brightness remains active e.g. for blue stretch
BLST	blue stretch	0 = off
		1 = on
YEXH	Y exclusive hue	0 = pin 26 is switched to hue adjust output
		1 = pin 26 is switched to Y output
RELC	relative to cut-off	0 = peak drive limit to absolute output
		1 = peak drive limit relative to cut-off
TCPL	time constant peak drive limiter	
		1 = 1f _H

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Note

 Matrix coefficients should be tested by comparing RGB output signals with a reference RGB colour bar, which is fed in at (RGB)₁ or (RGB)₂ inputs. In the event of NMEN = 1 (NTSC) at minimum saturation the Y output and RGB output signals are not identical to the Y input signal. PAL/SECAM signals are matrixed by the equation:

 $V_{G\,-\,Y} = -0.51 V_{R\,-\,Y} - 0.19 V_{B\,-\,Y}$

NTSC signals are matrixed by the equations (hue phase shift of -2 degrees):

 $V_{R-Y^*} = 1.39V_{R-Y} - 0.07V_{B-Y}$; $V_{G-Y^*} = -0.46V_{R-Y} - 0.15V_{B-Y}$; $V_{B-Y^*} = V_{B-Y}$ For demodulation axis see Fig.11.

In the matrix equations: V_{R-Y} and V_{B-Y} are conventional PAL demodulation axes and amplitudes at the output of the demodulator. V_{R-Y^*} , V_{G-Y^*} and V_{B-Y^*} are the NTSC-modified colour-difference signals.











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LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _P	supply voltage		-0.1	+9.0	V
V _{10, 11, 12}	(RGB) ₁ inputs	with respect to GND	-0.1	VP	V
V _{2, 3, 4}	(RGB) ₂ inputs	with respect to GND	-0.1	V _P	V
V _{8, 7, 6}	Y, CD-inputs	with respect to GND	-0.1	V _P	V
V _{13, 1}	switch 1 and switch 2 input voltage	with respect to GND	-0.1	VP	V
V _{25, 23, 21, 17}	black level, leakage storage	with respect to GND	-0.1	VP	V
V ₁₄	sandcastle	with respect to GND	-0.7	V _P + 5.8	V
V ₁₅	average current information	with respect to GND	-0.7	V _P + 0.7	V
V ₁₆	peak drive storage	with respect to GND	-0.1	VP	V
V ₁₈	peak dark storage	with respect to GND	-0.1	V _P	V
V ₁₉	cut-off control input voltage	with respect to GND	-0.7	V _P + 0.7	V
V _{27, 28}	I ² C-bus: SDA and SCL voltage	with respect to GND	-0.1	VP	V
I _{24, 22, 20}	output peak current		-20	-	mA
I _{24, 22, 20}	output average current		-10	-	mA
I ₂₆	Y output/hue adjust current		-8	-	mA
P _{tot}	total power dissipation		-	1200	mW
T _{amb}	operating ambient temperature		-20	+70	°C
T _{stg}	storage temperature		-20	+150	°C
V _{es}	electrostatic handling; note 1		-500	+500	V

Note

1. Charge device model class A: discharging a 200 pF capacitor through a 0 Ω series resistor.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	VALUE	UNIT
R _{th j-a}	thermal resistance from junction to ambient in free air	47	K/W

QUALITY SPECIFICATION

In accordance with URV-4-2-59/601. The number of the quality specification can be found in the "Quality Reference Handbook". The handbook can be ordered using the code 9397 750 00192.

CHARACTERISTICS

 $V_P = 8 \text{ V}$; $T_{amb} = +25 \text{ °C}$; V_{nom} : nominal signal amplitude (black-white) 2 000 mV (peak-to-peak value) at output pins; gamma = 1; adaptive black inactive; brightness, contrast, saturation and white balance at nominal settings; no beam current or peak drive limiting; all voltages are related to ground (pin 9) and measured in Figs 1 and 2; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _P	supply voltage (pin 5)		7.2	8	8.8	V
I _P	supply current (pin 5)		-	100	120	mA
	e inputs (–(Β – Υ): pin 6, –(R – Υ): pin 7; α n: maximum 600 Ω)	capacitively coupled to	a low-ol	hmic so	urce;	
V _{6(p-p)}	–(B – Y) signal (peak-to-peak value)	75% colour bar signal	-	1.33	-	V
V _{6,7}	internal bias during clamping		-	4.0	-	V
I _{6, 7}	DC input current between clamping pulses		-	-	0.1	μA
I _{6, 7}	maximum input current during clamping		100	180	260	μA
V _{7(p-p)}	-(R - Y) signal (peak-to-peak value)	75% colour bar signal	-	1.05	-	V
R _{6,7}	AC input resistance		10.0	-	-	MΩ
Y input (pin 8; ca	apacitively coupled to a low-ohmic sourc	e; recommendation: ma	aximum	600 Ω)		
V _{8(p-p)}	input signal (composite signal; VBS; peak-to-peak value)	adaption to two different signal levels via control bit YHI				
		YHI = 0	_	0.45	_	V
		YHI = 1	_	1.43	-	V
R ₈	AC input resistance		10.0	-	-	MΩ
V ₈	internal bias during clamping	YHI = 0	—	3.7	-	V
		YHI = 1	—	4.6	-	V
I ₈	DC input current between clamping pulses		-	-	0.1	μA
I _{8(max)(clamp)}	maximum input current during clamping		100	180	260	μA
• • •	pin 10, G ₁ : pin 11, B ₁ : pin 12; capacitive n: maximum 600 Ω); note 1	ly coupled to a low-ohm	nic sour	ce;	-	
V _{10, 11, 12(p-p)}	input signal (peak-to-peak value)		-	0.7	-	V
R _{10, 11, 12}	AC input resistance		10.0	-	-	MΩ
V _{10, 11, 12}	internal bias during clamping		-	5.1	-	V
I _{10, 11, 12}	DC input current between clamping pulses		-	-	0.1	μA
I _{10, 11, 12(clamp)}	maximum input current during clamping		100	180	260	μA

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
RGB input 2 (R ₂	: pin 2, G ₂ : pin 3, B ₂ : pin 4; capacitively c	oupled to a low-ohmic s	source;	1	1	4
• •	n: maximum 600 Ω); note 1	•	,			
V _{2, 3, 4(p-p)}	input signal (peak-to-peak value)		-	0.7	-	V
R _{2, 3, 4}	AC input resistance		10.0	_	-	MΩ
V _{2, 3, 4}	internal bias during clamping		-	5.1	-	V
I _{2, 3, 4}	DC input current between clamping pulses		-	-	0.1	μA
I _{2, 3, 4(max)(clamp)}	maximum input current during clamping		100	180	260	μA
Fast signal swite FSON1)	ches and blanking (fast signal switch 1 (p	bin 13); Y, CD / R ₁ , G ₁ , B ₁	; contro	ol bits F	SDIS1,	
V ₁₃	voltage to select Y and CD		-	0	0.4	V
V ₁₃	voltage range to select R_1 , G_1 and B_1		0.9	1.0	5.5	V
R ₁₃	internal resistor to ground		3.3	3.8	4.8	kΩ
CROSSTALK (SEE	TABLE 5)					
$t_s - t_i$	difference between transit times for signal switching and signal insertion		-	-	10	ns
Fast signal swite	ch 2 (pin 1; Y, CD or R ₁ , G ₁ , B ₁ / R ₂ , G ₂ , B ₂	; control bits FSDIS2, F	SON2)			1
V ₁	voltage to select Y and CD / R_1 , G_1 and B_1		-	0	0.4	V
V ₁	voltage range to select R_2 , G_2 and B_2		0.9	1.0	5.5	V
V ₁	required minimal voltage to switch off the ADBL measurement		-	0.87	1.0	V
R ₁	internal resistor to ground	R ₁ > R ₁₃	2.8	4.2	6.0	kΩ
CROSSTALK (SEE	TABLE 5)			•		
$t_s - t_i$	difference between transit times for signal switching and signal insertion		-	-	10	ns
Adjust stages (a	daptive black, gamma, contrast, saturation	on, brightness and white	e point a	adjust, I	blue str	etch)
ADAPTIVE BLACK (DETECTORS INACTIVE STATUS DUE TO ACTION	DF FAST SWITCH 2 (PIN 1):	see Tabl	le 4. Fia	.9 and n	ote 2)
I _{18(dch)}	discharge current of peak dark storage capacitor	outside active measurement window	-1.0	0.0	+1.0	μΑ
		inside active measurement window	1.5	2.5	3.5	μA
I _{18(ch)}	charge current of peak dark storage capacitor		-360	-300	-250	μA
d _{bl(max)}	maximum level shift: Δ black level in percent of nominal signal amplitude		10	13	16	%
d _{bl(nom)}	difference between nominal black and adaptive black in percent of nominal signal amplitude		-3	0	+3	%
t _{dibb}	detectors inactive time before blanking		2.3	3.1	4.0	μs
t _{diab}	detectors inactive time after blanking		2.3	2.5	3.4	μs

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
	CTS ON INTERNAL Y SIGNAL; Y MATRIX SEE ` I); RESOLUTION 6 BIT; note 3)	Y OUTPUT; I ² C-BUS CONTROLI	ED POT	ENTIOME	TER	1
dg	range of gamma					
	minimum (3FH)		_	0.7	-	-
	maximum (00H)		-	1.0	-	-
G _{max}	maximum gain at minimum gamma	near nominal black	5	6	7	dB
); resolution 1.5% of maximum saturat		ED POTE		TERS	
d _{s(max)}	maximum saturation	l ² C-bus data 3FH; measured at 100 kHz; relative to nominal saturation; note 4	4.7	5.2	5.8	dB
d _{s(min)}	minimum saturation	I ² C-bus data 00H; measured at 100 kHz; relative to typical value of maximum saturation	-	-	-50	dB
CONTRAST ADJUST 1.5% OF MAXIMUM	(ACTS ON RGB SIGNALS; I ² C-BUS CONTRC CONTRAST)	LLED POTENTIOMETERS (SUBA	DDRESS	s 02H); F	RESOLUT	ION
d _{c(max)}	maximum contrast	I ² C-bus data 3FH; limiters inactive; relative to nominal contrast; note 5	-	4.5	5.5	dB
d _{c(min)}	minimum contrast	I ² C-bus data 00H; relative to maximum contrast	-28	-22	-16	dB
	ST (ACTS ON RGB SIGNALS; I ² C-BUS CONTF BLACK LEVEL IN PERCENT OF NOMINAL SIGI					
d _{br(max)}	maximum brightness: Δ black level	I ² C-bus data 3FH	23	30	37	%
d _{br(nom)}	nominal brightness: Δ black level	I ² C-bus data 29H	-7	0	+7	%
d _{br(min)}	minimum brightness: Δ black level	I ² C-bus data 00H	-58	-50	-42	%
d _{br(max)}	maximum brightness: ∆ black level	I^2 C-bus data 3FH; control bits BCOF = 1 and MOD2 = 0	23	30	37	%
d _{br(min)}	minimum brightness: Δ black level	$I^{2}C$ -bus data 00H; control bits BCOF = 1 and MOD2 = 0	-58	-50	-42	%
BLUE STRETCH (BL	UE STRETCH IS ACTIVATED BY I ² C-BUS CON	TROL BIT BLST = 1; see Fig.	9)			
G _{bs}	increase of small signal gain	100% of nominal signal amplitude and at 1 MHz	15	20	25	%

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
(BLACK LEVEL CUT-	LACK LEVEL STEPS (DIFFERENCES FROM CHAN OFF MEASUREMENT LEVEL) TO ACTUAL NOMIN BRIGHTNESS AND SATURATION RANGE, SWITC 0)	AL SIGNAL AMPLITUDE (V_{NON}	₁₂₄ , V _{NO}	_{M22} , V _{NOM}	₄₂₀) OVE	R THE
$\Delta V/V_{nom}$	static deviation	note 6; ripple on pin 5 during clamping ≤1 mV; note 7	-1.0	-	+1.0	%
		at nominal saturation	-0.5	-	+0.5	%
RGB outputs (ou load)	tput for positive RGB signals (R: pin 24,	G: pin 2, B: pin 20); follo	owing c	lata witl	nout ext	ternal
R _{24, 22, 20}	differential output resistance		-	25	30	Ω
I _{24, 22, 20(max)}	maximum output current		4.0	5.0	-	mA
V _{24, 22, 20(min)}	minimum output voltage	note 8	-	-	0.8	V
V _{24, 22, 20(max)}	maximum output voltage	$R_L \ge 2 k\Omega$	6.3	7.0	_	V
V _{24, 22, 20(max)(p-p)}	maximum signal amplitude (black-white) due to internal limits (peak-to-peak value)		3.3	-	-	V
V ₂₄ , 22, 20(max)(p-p)	nominal signal amplitude (black-white; peak-to-peak value)	at nominal white adjust, contrast and saturation setting; gamma = 1; nominal input signals	1.7	2.0	2.3	V
V _{24, 22, 20}	cut-off measurement level	note 8	1.0	-	5.0	V
V _{24, 22, 20}	recommended cut-off measurement level		-	3.0	-	V
OUTPUT CLAMPING	(RGB)					
V _{20, 22, 24}	clamp voltage black level	control bit BCOF = 1	2.3	2.5	2.7	V
WHITE POTENTIOME	ETERS	1		1	1	4
$\Delta G_{v(inc)(max)}$	maximum increase of AC gain	I ² C-bus data 3FH; relative to nominal setting; note 9	40	50	60	%
$\Delta G_{v(dec)(max)}$	maximum decrease of AC gain	I ² C-bus data 00H; relative to nominal setting; note 9	40	50	60	%

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
OVERALL WHITE F	POINT DEVIATION		1			4
ΔV/V _{nom}	note 10	input: (RGB) _{1, 2} ; differences from channel to channel of the ratio of the difference (signal white level cut-off measurement level) to actual nominal signal amplitude (V_{nom24} , V_{nom22} , V_{nom20}) over the whole saturation range at nominal contrast, brightness and nominal input signals; ripple on pin 5 during clamping ≤1 mV; note 7	-2.0	-	+2.0	%
Frequency beha	aviour			1	•	
BETWEEN THE Y	INPUT (PIN 8) AND THE RGB OUTPUTS (PINS 2	24, 22 and 20)				
ΔG	decrease in gain	1 M Ω and 20 pF load at 13 MHz	-	-	3	dB
BETWEEN THE CO	DLOUR-DIFFERENCE INPUTS (PINS 7 AND 6) AN	D THE CORRESPONDING R AN	D B OUT	IPUTS (P	INS 24 A	.ND 20)
ΔG	decrease in gain	at 13 MHz	-	-	3	dB
BETWEEN THE (R	GB) _{1, 2} INPUTS (PINS 10, 11 AND 12 OR 2, 3	AND 4) AND THE RGB OUTPU	TS (PINS	324, 22	and 20)	
ΔG	decrease in gain	at 22 MHz	-	-	3	dB
Sandcastle inp	ut (pin 14; control bit SC5); note 11					
I ₁₄	input current	V ₁₄ < 0.5 V	-100	-	-	μA
C ₁₄₋₉	input capacitance		-	-	10	pF
V ₁₄	required voltage range for horizontal and vertical blanking pulses	SC5 = 0 or SC5 = 1	2.0	2.5	3.0	v
	for horizontal pulses (line count)	SC5 = 0	4.0	4.5	4.9	V
	for burst key pulses	SC5 = 0	6.1	-	V _P + 5.8	V
	for burst key pulses and line count	SC5 = 1	4.0	-	V _P + 5.8	V

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
CLAMP PULSE DEI	LAY					1
T _{d(clamp)}	delay of leading edge of clamping pulse	nominal sandcastle pulse DELOF = 0	1.2	1.5	1.8	μs
		DELOF = 1	-	0	-	μs
t _W	DELOF = 0	line frequency: 16 kHz	3	-	-	μs
	DELOF = 1	line frequency: 32 kHz	1.5	-	-	μs
	neasurement lines and blanking; note 12	1	-1		1	
$\Delta V/V_{nom}$	$\Delta V = VCL - VUB$ difference between ultra black level (VUB) and measurement level (VCL) in percent of nominal signal amplitude	no clipping; independent of white point adjust	25	35	45	%
WARM UP TEST P	ULSE DURING MT (see pulse diagram Fig.10)			•		
V _{WU}	warm up level	$V_{WU} = V_{PL} - 1 V;$ $V_{PL} = \text{peak drive level}$ (see also signal limiting); given by I ² C-bus; subaddress 0AH; no warm up test pulse in the event of output clamping (BCOF = 1)	_	-	-	-
V _{WU(max)}	maximum warm up level	I ² C-bus data 3FH; RELC = 0	6.3	6.6	6.9	V
V _{WU(fixed)}	fixed warm up level	RELC = 1	5.0	5.2	5.4	V
THRESHOLD FOR	POWER ON RESET (POR) DURING TIME DG (S	ee pulse diagram Fig.10)		•		
V _{20, 22, 24} (POR)	output voltage to cause POR	RELC = 0	-	V _{PL}	-	V
		RELC = 1	-	5.7	-	V
Y output (pin 26	5; note 13)					
V _{26(nom)(p-p)}	nominal signal amplitude (black-white; independent of gamma, adaptive black, saturation, contrast and brightness; peak-to-peak value)	control bit YEXH = 1; hue DAC (subaddress 03H) set to >28H	0.85	1.0	1.15	V
V ₂₆	black level	YEXH = 1; I ² C-bus data 3FH	-	4.0	-	V
		YEXH = 1; I ² C-bus data 20H	-	2.0	-	V
a _r	Y matrix coefficients	$Y = a_r R + a_g G + a_b B$	0.27	0.30	0.33	<u> </u>
a _g	Y matrix coefficients	$Y = a_r R + a_g G + a_b B$	0.53	0.59	0.65	L
a _b	Y matrix coefficients	$Y = a_r R + a_g G + a_b B$	0.10	0.11	0.12	

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
R ₂₆	differential output resistance		_	190	230	Ω
$\Delta \tau_{26}$	group delay time	between RGB outputs and Y output	20	25	30	ns
fg	3 dB bandwidth		11	15	-	MHz
Automatic cut-c	off control (pin 19; measurement periods	see beam info on pin 19)				
V ₁₉	permissible voltage (also during scanning period)		-	-	V _P – 1.4	V
V _{REF0}	internally controlled voltage on pin 19	during leakage measurement time LM	2.4	2.7	3.0	V
I _{o19(max)}	maximum output current		-350	-	-250	μA
I _{i19(max)}	maximum input current		250	-	350	μA
R ₁₉	input resistance for measurement input		1	-	-	MΩ
I ₁₉	additional input current	only during warm up	-	0.5	-	mA
V ₁₉	threshold of warm up detector (active in line MG)		4.3	4.5	4.7	V
V _{MEAS}	difference between input voltage for cut-off and V_{REF0} ; adjustable via I^2 C-bus (subaddress for reference: R: 07H, G: 08H and B: 09H)		_	_	-	-
	maximum V _{MEAS}	I ² C-bus data 3FH	1.45	1.6	1.75	V
	nominal V _{MEAS}	I ² C-bus data 20H	0.9	1.0	1.1	V
	minimum V _{MEAS}	I ² C-bus data 00H	0.4	0.45	0.5	V
Storage of cut-o	off control voltage / output clamping volta	ge (pins 25, 23 and 21)				
I _{25, 23, 21}	input currents of storage inputs outside of the measurement time		-	-	0.1	μA
I _{25, 23, 21(max)}	maximum charge / discharge current during measurement time		0.2	0.3	0.4	mA
G _{stg}	gain from storage pins 25, 23 and 21 to outputs		-	1.7	-	-
Storage of leaka	age information (pin 17)					
I ₁₇	maximum charge / discharge current at time LM		300	400	-	μA
I ₁₇	discharge current	peak limiting during time MK active	-	4	-	mA
I ₁₇	leakage current	outside time LM	_	_	0.1	μA
V ₁₇	voltage to reset IC to switch on conditions	V ₁₇ is below	2.3	2.5	3.0	V

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Signal limiting (t	he limitation acts on contrast and at low	contrast on brightness)	1	ļ	1	-
AVERAGE BEAM CU	IRRENT LIMITING (PIN 15)					
V ₁₅	start of contrast reduction		_	4	_	V
ΔV_{15}	input range for full contrast reduction		-	-2	_	V
V ₁₅	start of brightness reduction		-	2.5	-	V
ΔV_{15}	input range for full brightness reduction		-	-1.6	-	V
I ₁₅	input current		-	_	-0.5	μA
	ING OF OUTPUT SIGNALS (PIN 16; THE LIMITAT RESS 0AH; CONTROL BIT RELC = 0))	ION ACTS 1H DELAYED; LIMIT	TING LEV	EL ADJU	STABLE E	3Y
V _{24, 22, 20(max)}	maximum limiting level	extrapolated from 2FH	6.8	-	7.2	V
V _{24, 22, 20(min)}	minimum limiting level	I ² C-bus data 00H	-	2.3	3	V
I _{16(max)}	maximum discharge current at peak drive	RELC = 0	4	-	6	mA
PEAK SIGNAL LIMIT	ING (PIN 16; CONTROL BIT RELC = 1; LIMITING	G LEVEL (V _{LIL}) ADJUSTABLE E	у I ² C-в	US (SUBA	ADDRESS	。 0AH))
V _{LiL}		equal gain in white point adjust; signal only in one output channel; peak drive limiting starts, if the maximum of the RGB signals after white point adjustment exceeds a threshold				
	maximum limiting level	I ² C-bus data 3FH	3.2	3.5	4.0	V
	minimum limiting level	I ² C-bus data 00H	1.2	1.5	1.8	V
DISCHARGE CURRE	ENTS (CUT-OFF MEASUREMENT LEVEL $MX = N$	R or MB or MG)				
I _{16(tot)(dch)}	total discharge current	$I_{16} = I_{16(1)} + I_{16(2)} + I_{16(3)}$	-	_	-	_
Threshold 1 (TH1)					
I _{16(1)(max)(dch)}	maximum discharge current	TH1 = MX + V _{LiL} ; 1 line delayed and low-pass filtered	4.5	6	7.5	mA
S	steepness		-	15	-	mA/V
Low-pass filter, co	ontrol bit TCPL		•	•	•	
t _{DPDL}	time constant low-pass filter	TCPL = 1 (at 1f _H); RELC = 1	0.9	1.2	1.5	μs
t _{DPDL}	time constant low-pass filter	TCPL = 0 (at 2f _H); RELC = 1	0.4	0.6	0.8	μs
Threshold 2 (TH2)					
I _{16(2)(max)(dch)}	maximum discharge current	TH2 = MX + $V_{LiL} \times 1.10$; 1 line delayed	4.5	6	7.5	mA
S	steepness		_	15	_	mA/V

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Threshold 3 (TH3	3)		I			4
I _{16(3)(max)(dch)}	maximum discharge current	TH3 = MX + V _{LiL} ; undelayed	0.45	0.6	0.75	mA
S	steepness		_	1.5	-	mA/V
CHARGE CURRENT	-					-
I ₁₆	charge current		-2	-1	-0.5	μA
V ₁₆	start of contrast reduction		_	4	-	V
ΔV_{16}	input range for full contrast reduction		_	-2	-	V
V ₁₆	start of brightness reduction		_	2.5	-	V
ΔV_{16}	input range for full brightness reduction		_	-1.6	-	V
V _{16(max)}	maximum voltage by internal limitation		4.5	_	-	V
Hue adjust outp	ut (pin 26); note 14					•
V _{o26(min)}	minimum output voltage	YEXH = 0; I^2 C-bus data 00H	0.5	-	1.0	V
V _{o26(nom)}	nominal output voltage	YEXH = 0; I ² C-bus data 20H	3.0	3.2	3.4	V
V _{o26(max)}	maximum output voltage	YEXH = 0; I ² C-bus data 3FH	4.8	-	5.6	V
I ₂₆	current of internal emitter follower		500	700	-	μA
I ² C-bus inputs						
f ₂₈	clock frequency range		0	_	100	kHz
t _{SU;DAT}	data set-up time		250	_	-	ns
t _H	clock pulse HIGH		4	-	-	μs
tL	clock pulse LOW		4.7	-	-	μs
t _r	rise time		_	_	1	μs
t _f	fall time		-	_	0.3	μs
Input levels (pin	s 27 and 28)					-
V _{IL}	LOW level input voltage		-	-	1.5	V
V _{IH}	HIGH level input voltage		3.0	_	5.5	V
l _l	input current	V ₂₇ and V ₂₈ = 0.4 V	-10	-	-	μA
		$V_{\rm 27}$ and $V_{\rm 28}$ = 0.9V $_{\rm P}$	-	_	10	μA
Output level (pir	1 27)					
V _{OL}	LOW level output voltage		_	-	0.4	V
	output current	V ₂₇ = 0.4 V	3.0	_	_	mA

TDA4780

Notes to the characteristics

- 1. RGB signals controlled by saturation, adaptive black, contrast and brightness. Gamma affects the Y component of the internal RGB signals.
- 2. Adaptive black control acts on Y signal, which is either Y input or Y output from RGB matrix. Negative set-up is not affected. The level shift value is determined by the peak dark detector, operation selected by control bit ADBL. The peak dark detector is inactive during blanking. Peak dark detector activated by internal line counter, which starts after the end of the vertical blank of the sandcastle. Active from line 16 (after end of vertical sandcastle) to line 224 (NTSC mode, NMEN = 1) or line 272 (PAL mode, NMEN = 0). It is recommended to increase the contrast value (subaddress 02H) by 15% if ADBL = 1. The line numbers are doubled if control bit HDTV = 1.
- 3. At minimum gamma (3FH) any differences in black level steps are amplified by 6 dB.
- 4. For nominal saturation the range of values is:
 - a) 1FH is the minimum value that can be used
 - b) 20H is the typical value that can be used
 - c) 21H is the maximum value that can be used.
- 5. For nominal contrast the range of values is:
 - a) 20H is the minimum value that can be used
 - b) 22H is the typical value that can be used
 - c) 24H is the maximum value that can be used.

6.
$$\frac{\Delta V}{V_{nom}} = \frac{\Delta V_{24}}{V_{nom24}} - \frac{\Delta V_{22}}{V_{nom22}} = \frac{\Delta V_{24}}{V_{nom24}} - \frac{\Delta V_{20}}{V_{nom20}} = \frac{\Delta V_{22}}{V_{nom22}} - \frac{\Delta V_{20}}{V_{nom20}}$$
. For meaning of actual nominal signal see chapter "Characteristics".

7. Series resistor in supply voltage should be less than 0.3 Ω .

- At 1.0 V cut-off measurement level the function of the cut-off control loop is not guaranteed because the blanking level is limited to the minimum output voltage. For proper working a guide number for the minimum cut-off measurement level is 1.3 V.
- 9. For nominal AC gain settings the range of values is:
 - a) 21H is the minimum value that can be used
 - b) 22H is the typical value that can be used
 - c) 23H is the maximum value that can be used.

10.
$$\frac{\Delta V}{V_{nom}} = \frac{\Delta V_{24}}{V_{nom24}} - \frac{\Delta V_{22}}{V_{nom22}} = \frac{\Delta V_{24}}{V_{nom24}} - \frac{\Delta V_{20}}{V_{nom20}} = \frac{\Delta V_{22}}{V_{nom22}} - \frac{\Delta V_{20}}{V_{nom20}}$$
. For meaning of actual nominal signal see

chapter "Characteristics".

11. Sandcastle pulse detector (pin 14)

The sandcastle pulse is compared with 3 (control bit SC5 = 0) or 2 (SC5 = 1) internal threshold levels to separate the various pulses; the internal pulses are generated while the input is higher than the thresholds. The thresholds are independent of supply voltage and temperature.

- 12. Blanking to ultra black level occurs during time DG except MR in R-channel, MG in G-channel, MB in B-channel (see Fig.10).
 - a) Leakage current measuring time: LM will start after the end of vertical sandcastle (see Fig.10).
 - b) Vertical blanking period and cut-off measurement lines (see Fig.10): The vertical component will be identified if it contains 2 or more burst key pulses in the event of SC5 = 1 or two or more line pulses (H) in the event of SC5 = 0. The line counter is triggered by the leading edge. The blanking time is valid for a vertical pulse detected by the sandcastle decoder. The internal blank pulse is OR gated with the sandcastle vertical pulse and the end of the measurement pulses.
 - c) Insertion time: full line period.
 - d) Measurement time: line period minus horizontal period (50/60 Hz).
 - e) Line sequence of measuring lines (see Fig.10): First line after end of horizontal pulse which followed the end of vertical pulse: leakage measurement LM First line after leakage measurement pulse: red measurement MR Second line after leakage measurement pulse: green measurement MG Third line after leakage measurement pulse: blue measurement MB.
- 13. Y output can be switched to hue adjust output via I²C-bus control bit YEXH. Output without sync pulse. Recommendation: Hue adjust DAC set to 3FH. Black level adjustable via hue adjust DAC.
- 14. Output can be switched to Y output via I²C-bus control bit YEXH (via I²C-bus, resolution 6-bit, bus subaddress 03H).

INTERNAL PIN CONFIGURATIONS

Abbreviations: OB: Open Base and CL: Clamp Pulse.





PIN	PIN NAME (DESCRIPTION)	WAVE FORM	l or Z	INTERNAL CIRCUIT
7	colour difference input –(R – Y)	4 V colour bars	100 μA/OB	CL CL CL CL CL CL CL CL CL CL CL CL CL C
8	luminance input	5 V black colour bars from the second	100 μA/OB	CL CL ESD Protection 8 MGE896
9	ground			9 GND MGE897 no ESD protection circuit for ground pin



PIN	PIN NAME (DESCRIPTION)	WAVE FORM	l or Z	INTERNAL CIRCUIT
13	fast switch 1 input			C = 2 mA 0.2 mA (13) 3.8 kΩ FSD protection (13) MGE904
14	sandcastle pulse input	3-level sandcastle $CL \rightarrow f 5.5 V$ $H \rightarrow 3.5 V$ $V \rightarrow 1.5 V$ MGE905 2-level sandcastle $CL \rightarrow 3.5 V$ $HV \rightarrow 1.5 V$ MGE906	37 kΩ (SC5 = 0) OB (SC5 = 1)	+ 50 μA + + + + + + + +
15	average beam current limiting input		OB	$\begin{array}{c} + \\ - \\ - \\ - \\ - \\ - \\ - \\ - \\ - \\ - \\$

PIN	PIN NAME (DESCRIPTION)	WAVE FORM	l or Z	INTERNAL CIRCUIT
16	storage capacitor	outside peak drive	ОВ	
	for peak limiting	during peak drive (RELC = 1)	0 to 12 mA	
		during peak drive (RELC = 0)	5 mA	$30 \mu A$ $2 k\Omega$ 0 to 12 mA 4.2 V 0 to 12 mA 4.2 V 16 drive detection 6 FSD protection MGE909
17	storage capacitor for leakage current	outside leakage current measurement	ОВ	+-+-
	compensation	during leakage current measurement	–400 μA to +400 μA	
		automatic switch to power on reset	4 mA	2.5 V 2.5 V 4 mA 5 witch to 5 power on reset 17 FSD 17 MGE910

PIN	PIN NAME (DESCRIPTION)	WAVE FORM	l or Z	INTERNAL CIRCUIT
18	storage capacitor for peak dark		OB/0.26 mA	0.26 mA closed switch if peak dark detected
19	cut-off measurement input	3.7 V MR MG MB	–300 μA to +300 μA	

PIN	PIN NAME (DESCRIPTION)	WAVE FORM	l or Z	INTERNAL CIRCUIT
20	blue output	BCOF = 0 1st line , sawtooth , cut-off signal , pulse brightness , ultra black	5 mA 5 mA	ESD protection 20 MGE917
		BCOF = 1 MOD2 = 1 2.5 V MGE916	5 mA	
21	blue cut-off storage capacitor	during cut-off control or during output clamping	OB -300 μA to +300 μA	= 2.5 V $= 2.5 V$

PIN	PIN NAME (DESCRIPTION)	WAVE FORM	l or Z	INTERNAL CIRCUIT
22	green output	BCOF = 0 1st line / sawtooth / cut-off signal / pulse brightness / ultra black //	5 mA 5 mA	ESD protection 22
		BCOF = 1 MOD2 = 0 brightness 2.5 V MGE920 BCOF = 1 MOD2 = 1	5 mA	MGE922
		2.5 V		
23	green cut-off storage capacitor	during cut-off control or during output clamping	OB -300 μA to +300 μA	= 2.5 V $= 2.5 V$

PIN	PIN NAME (DESCRIPTION)	WAVE FORM	l or Z	INTERNAL CIRCUIT
24	red output	BCOF = 0 1st line / sawtooth / cut-off signal / pulse brightness / ultra black //	5 mA	↓ ↓ 24 ↓ 5 mA ↓ ESD
		BCOF = 1 MOD2 = 0 brightness	5 mA	Protection (24)
		BCOF = 1 MOD2 = 1 2.5 V MGE926	5 mA	
25	red cut-off storage capacitor	during cut-off control or during output clamping	OB -300 μA to +300 μA	= 2.5 V $= 2.5 V$ $= 2.$

PIN	PIN NAME (DESCRIPTION)	WAVE FORM	l or Z	INTERNAL CIRCUIT
26	Y output/hue adjust output	YEXH = 1 	0.7 mA	0.7 mA
		YEXH = 0; DC 0.8 V to 5.0 V	0.7 mA	ESD protection (26) MGE930
27	I ² C-bus serial data input/acknowledge output	outside acknowledge during acknowledge	OB less than 0.1 V up to 4 mA due to external pull-up resistor	+ $10 \mu A$ $2 k\Omega$ $2 k\Omega$ 27 acknowledge 27 acknowledge 27 acknowledge 27 acknowledge 27 acknowledge 27 acknowledge 27 acknowledge
28	I ² C-bus serial clock input		OB	$\begin{array}{c} + \\ + \\ + \\ + \\ + \\ + \\ + \\ + \\ + \\ 2 \\ k\Omega \\ \hline \\ 28 \\ \hline \\ \hline \\ \\ \hline \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ $

TEST AND APPLICATION INFORMATION



PACKAGE OUTLINE

DIP28: plastic dual in-line package; 28 leads (600 mil)

seating plane MF A₂ Ą Ť L A₁ ⊕ w M е b₁ (e₁ b 28 15 M_H pin 1 index F 1 14 10 mm 5 0 scale DIMENSIONS (inch dimensions are derived from the original mm dimensions) Z ⁽¹⁾ A max. A₁ min A₂ max. D⁽¹⁾ E⁽¹⁾ UNIT M_H b L Μ_E b₁ с е e₁ w max. 3.9 0.53 0.32 36.0 15.80 17.15 1.7 14.1 0.51 4.0 0.25 mm 5.1 2.54 15.24 1.7 1.3 0.38 0.23 35.0 3.4 15.24 15.90 13.7 0.066 0.020 0.013 0.56 0.15 0.68 1.41 0.62 inches 0.020 0.01 0.067 0.20 0.16 0.10 0.60 0.051 0.014 0.009 1.34 0.54 0.13 0.60 0.63 Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE	REFERENCES				EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT117-1	051G05	MO-015AH				-92-11-17 95-01-14

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SOT117-1

SOLDERING

Introduction

There is no soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and surface mounted components are mixed on one printed-circuit board. However, wave soldering is not always suitable for surface mounted ICs, or for printed-circuits with high population densities. In these situations reflow soldering is often used.

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our *"IC Package Databook"* (order code 9398 652 90011).

Soldering by dipping or by wave

The maximum permissible temperature of the solder is 260 °C; solder at this temperature must not be in contact with the joint for more than 5 seconds. The total contact time of successive solder waves must not exceed 5 seconds.

The device may be mounted up to the seating plane, but the temperature of the plastic body must not exceed the specified maximum storage temperature ($T_{stg\,max}$). If the printed-circuit board has been pre-heated, forced cooling may be necessary immediately after soldering to keep the temperature within the permissible limit.

Repairing soldered joints

Apply a low voltage soldering iron (less than 24 V) to the lead(s) of the package, below the seating plane or not more than 2 mm above it. If the temperature of the soldering iron bit is less than 300 °C it may remain in contact for up to 10 seconds. If the bit temperature is between 300 and 400 °C, contact may be up to 5 seconds.

DEFINITIONS

Data sheet status					
Objective specification	This data sheet contains target or goal specifications for product development.				
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.				
Product specification	This data sheet contains final product specifications.				
Limiting values					
more of the limiting values m of the device at these or at a	Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.				
Application information					
Where application information is given, it is advisory and does not form part of the specification.					

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